

SmartMesh IP Access Point (AP) Mote 2.4GHz 802.15.4e Wireless AP Mote

NETWORK FEATURES

- Complete Radio Transceiver, Embedded Processor, and Networking Software for Forming a Self-Healing Mesh Network
- SmartMesh® Networks Incorporate:
 - Time Synchronized Network-Wide Scheduling
 - Per-Transmission Frequency Hopping
 - Redundant Spatially Diverse Topologies
 - Network-Wide Reliability and Power Optimization
 - NIST Certified Security
- SmartMesh Networks Deliver:
 - >99.999% Network Reliability Achieved in the Most Challenging RF Environments
 - Sub 50µA Routing Nodes
- Compliant to 6LoWPAN Internet Protocol (IP) and IEEE 802.15.4e Standards

LTC5800-IPA FEATURES

- Provides Network Access Point Radio Functions for SmartMesh VManager
- Supports Networks of Thousands of Nodes, in Combination with VManager Network Management Software
- Enables Redundant Network Ingress/Egress with Automatic Failover
- PCB Module Versions Available (LTP®5901/2-IPA) with RF Modular Certifications
- 72-Lead 10mm × 10mm QFN Package

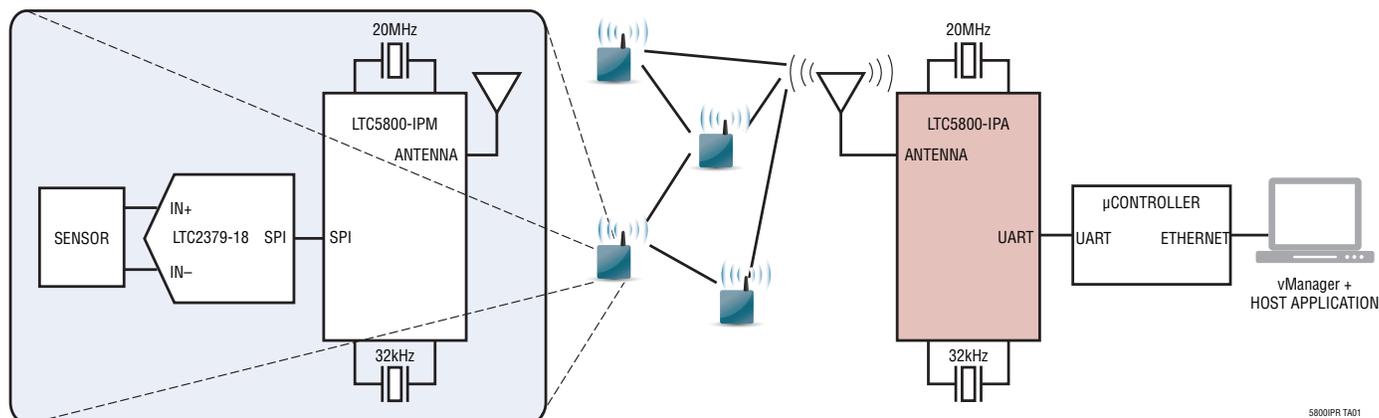
DESCRIPTION

SmartMesh IP™ wireless sensor networks are self managing, low power internet protocol (IP) networks built from wireless nodes called motes. The LTC®5800-IPA is the IP Access Point Mote™ (AP Mote™) in the Eterna®* family of IEEE 802.15.4e system-on-chip (SoC) solutions, featuring a highly integrated, low power radio design by Dust Networks® as well as an ARM Cortex-M3 32-bit microprocessor running Dust’s embedded SmartMesh IP networking software. SmartMesh IP software provided with the LTC5800-IPA is a fully tested and validated binary image.

Based on the IETF 6LoWPAN and IEEE-802.15.4e standards the LTC5800-IPA SoC, executing SmartMesh IP Access Point Mote software, provides a data ingress/egress point via a two wire UART interface. In combination with the VManager™ software, the LTC5800-IPA enables very large scale networks with full redundancy and automatic failover, in addition to providing a means to scale network throughput. With Dust’s time-synchronized SmartMesh IP networks, all motes in the network may route, source or terminate data, while providing many years of battery-powered operation.

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* Eterna is Dust Networks’ low power radio SoC architecture.

TYPICAL APPLICATION



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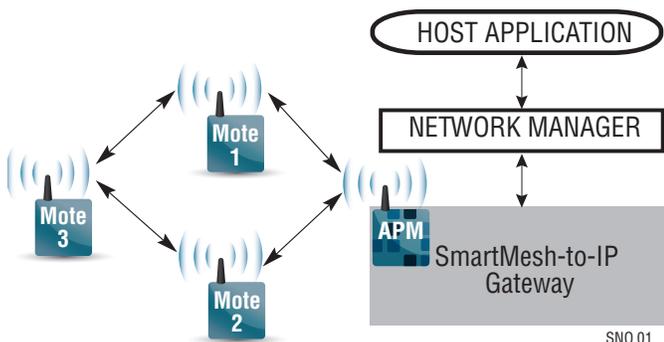
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SMARTMESH NETWORK OVERVIEW

A SmartMesh network consists of a self-forming multi-hop mesh of nodes, known as motes, which collect and relay data, and a network manager that monitors and manages network performance and security and exchanges data with a host application.

SmartMesh networks communicate using a time slotted channel hopping (TSCH) link layer, pioneered by Dust Networks. In a TSCH network, all motes in the network are synchronized to within less than a millisecond. Time in the network is organized into time slots which enable collision-free packet exchange and per-transmission channel-hopping. In a SmartMesh network, every device has one or more parents (e.g., mote 3 has motes 1 and 2 as parents) that provide redundant paths to overcome communications interruption due to interference, physical obstruction or multi-path fading. If a packet transmission fails on one path, the next retransmission may try on a different path and different RF channel.

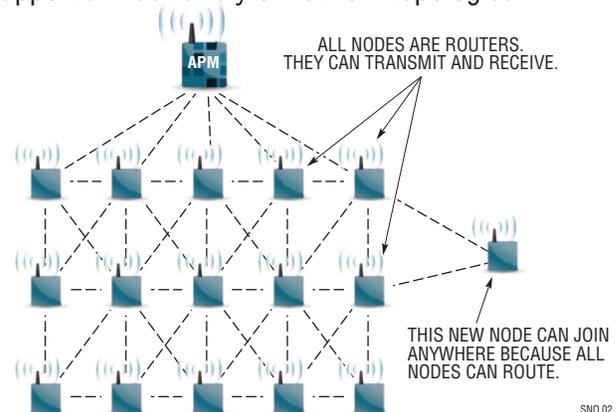
A network begins to form when the network manager instructs its AP Mote to begin sending advertisements—packets that contain information that enables a device to synchronize to the network and request to join. This message exchange is part of the security handshake that establishes encrypted communications between the manager or application, and mote. Once motes have joined the network, they maintain synchronization through time corrections when a packet is acknowledged.



An ongoing discovery process ensures that the network continually discovers new paths as the RF conditions change. In addition, each mote in the network tracks performance statistics (e.g., quality of used paths and lists of potential paths) and periodically sends that information to the network manager in packets called health reports.

The network manager uses health reports to continually optimize the network to maintain >99.999% data reliability even in the most challenging RF environments.

The use of TSCH allows SmartMesh devices to sleep in-between scheduled communications and draw very little power in this state. Motes are only active in time slots where they are scheduled to transmit or receive, typically resulting in a duty cycle of <1%. The optimization software in the Network Manager coordinates this schedule automatically. When combined with the Eterna low power radio, every mote in a SmartMesh network—even busy routing ones—can run on batteries for years. By default, all motes in a network are capable of routing traffic from other motes, which simplifies installation by avoiding the complexity of having distinct routers vs non-routing end nodes. Motes may be configured as non-routing to further reduce that particular mote's power consumption and to support a wide variety of network topologies.



At the heart of SmartMesh motes and AP motes is the Eterna IEEE 802.15.4e system-on-chip (SoC), featuring Dust Networks' highly integrated, low power radio design, plus an ARM Cortex-M3 32-bit microprocessor running SmartMesh networking software. The SmartMesh networking software comes fully compiled yet is configurable via a rich set of application programming interfaces (APIs) which allows a host application to interact with the network, e.g., to transfer information to a device, to configure data publishing rates on one or more motes, or to monitor network state or performance metrics. Data publishing can be uniform or different for each device, with motes being able to publish infrequently or faster than once per second as needed. For a complete description of the system, refer to the [SmartMesh IP User's Guide](#).

LTC5800-IPA

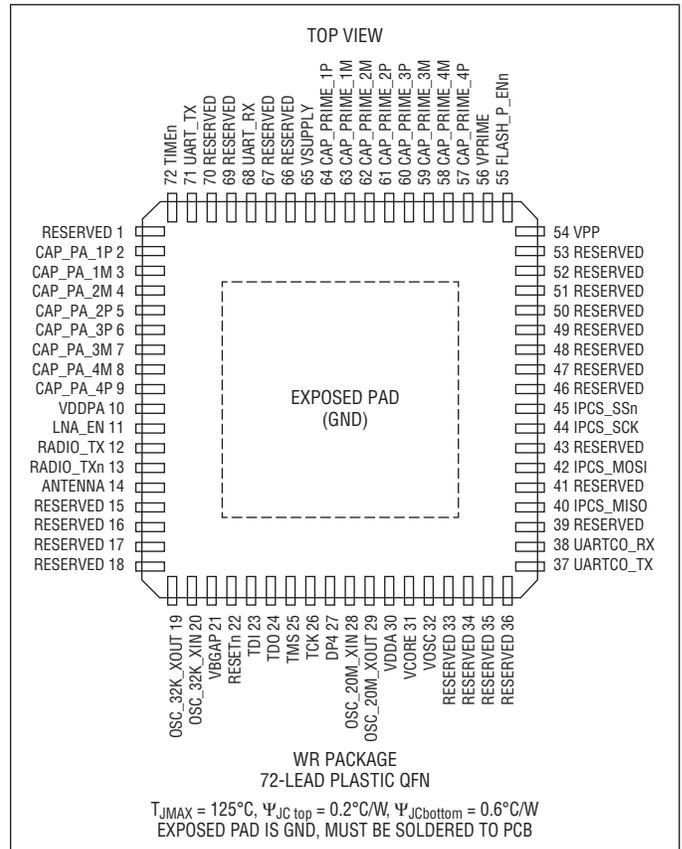
ABSOLUTE MAXIMUM RATINGS

(Note 1)

Supply Voltage on VSUPPLY	4.20V
Voltage on Any Digital I/O pin..-0.3V to VSUPPLY + 0.3V	
Input RF Level	10dBm
Storage Temperature Range (Note 3).....	-55°C to 125°C
Junction Temperature (Note 3)	125°C
Operating Temperature Range	
LTC5800I	-40°C to 85°C
LTC5800H.....	-55°C to 105°C

CAUTION: This part is sensitive to electrostatic discharge (ESD). It is very important that proper ESD precautions be observed when handling the LTC5800-IPA.

PIN CONFIGURATION



ORDER INFORMATION <http://www.linear.com/product/LTC5800-IPA#orderinfo>

LEAD FREE FINISH	PART MARKING*	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE
LTC5800IWR-IPMA#PBF	LTC5800WR-IPMA	72-Lead (10mm × 10mm × 0.85mm) Plastic QFN	-40°C to 85°C
LTC5800HWR-IPMA#PBF	LTC5800WR-IPMA	72-Lead (10mm × 10mm × 0.85mm) Plastic QFN	-55°C to 105°C

Purchase of LTC5800xWR-IPMA#PBF components includes access to download Access Point Mote software via <https://www.linear.com/mylinear/login.php>.

*The temperature grade is identified by a label on the shipping container.

For more information on lead free part marking, go to: <http://www.linear.com/leadfree/>

For more information on tape and reel specifications, go to: <http://www.linear.com/tapeandree/>. Some packages are available in 500 unit reels through designated sales channels with #TRMPBF suffix.

RECOMMENDED OPERATING CONDITIONS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^{\circ}\text{C}$. VSUPPLY = 3.6V unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
VSUPPLY	Supply Voltage	Including Noise and Load Regulation	● 2.1		3.76	V
	Supply Noise	Requires Recommended RLC Filter, 50Hz to 2MHz	●		250	mV
	Operating Relative Humidity	Non-Condensing	● 10		90	% RH
	Temperature Ramp Rate While Operating in Network	-40°C ≤ Temperature ≤ 85°C	-8		8	°C/Min
		Temperature > 85°C or Temperature < -40°C	-1		1	°C/Min

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DC CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^\circ\text{C}$. $V_{\text{SUPPLY}} = 3.6\text{V}$ unless otherwise noted.

OPERATION/STATE	CONDITIONS	MIN	TYP	MAX	UNITS
Power-On Reset	During Power-On Reset, Maximum $750\mu\text{s} + V_{\text{SUPPLY}}$ Rise Time from 1V to 1.9V		12		mA
In-Circuit Programming	RESETn and FLASH_P_ENn Asserted, IPCS_SCK at 3.33MHz		20		mA
Peak Operating Current 8dBm 0dBm	System Operating at 14.7MHz, Radio Transmitting, During Flash Write. Maximum Duration 4.33ms		30 26		mA mA
Active	ARM Cortex M3, RAM and Flash Operating, Radio and All Other Peripherals Off. Clock Frequency of CPU and Peripherals Set to 14.3728MHz, $V_{\text{CORE}} = 1.2\text{V}$		2.6		mA
Flash Write	Single Bank Flash Write		3.7		mA
Flash Erase	Single Bank Page or Mass Erase		2.5		mA
Radio Tx +0dBm (LTC5800I) +0dBm (LTC5800H) +8dBm (LTC5800I) +8dBm (LTC5800H)	Current With Autonomous MAC Managing Radio Operation, CPU Inactive. Clock Frequency of CPU and Peripherals Set to 14.3728MHz.		5.9 6.1 10.2 10.4		mA mA mA mA
Radio Rx LTC5800I LTC5800H	Current With Autonomous MAC Managing Radio Operation, CPU Inactive. Clock Frequency of CPU and Peripherals Set to 14.3728MHz.		5.0 5.2		mA mA

TEMPERATURE SENSOR CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^\circ\text{C}$. $V_{\text{SUPPLY}} = 3.6\text{V}$ unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Offset	Temperature Offset Error at 25°C		± 0.25		$^\circ\text{C}$
Slope Error			± 0.033		$^\circ\text{C}/^\circ\text{C}$

RADIO SPECIFICATIONS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^\circ\text{C}$. $V_{\text{SUPPLY}} = 3.6\text{V}$ unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Frequency Band		● 2.4000		2.4835	GHz
Number of Channels		●	15		
Channel Separation		●	5		MHz
Channel Center Frequency	Where $k = 11$ to 25 , as Defined by IEEE.802.15.4	●	$2405 + 5 \cdot (k - 11)$		MHz
Modulation	IEEE 802.15.4 Direct Sequence Spread Spectrum (DSSS)				
Raw Data Rate		●	250		kbps
Antenna Pin ESD Protection	HBM Per JEDEC JESD22-A114F		± 1000		V
Range (Note 4) Indoor Outdoor Free Space	25°C , 50% RH, 2dBi Omnidirectional Antenna, Antenna 2m Above Ground		100 300 1200		m m m

RADIO RECEIVER CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^\circ\text{C}$. $V_{\text{SUPPLY}} = 3.6\text{V}$ unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Receiver Sensitivity	Packet Error Rate (PER) = 1% (Note 5)		-93		dBm
Receiver Sensitivity	PER = 50%		-95		dBm
Saturation	Maximum Input Level the Receiver Will Properly Receive Packets		0		dBm
Adjacent Channel Rejection (High Side)	Desired Signal at -82dBm, Adjacent Modulated Channel 5MHz Above the Desired Signal, PER = 1% (Note 5)		22		dBc
Adjacent Channel Rejection (Low Side)	Desired Signal at -82dBm, Adjacent Modulated Channel 5MHz Below the Desired Signal, PER = 1% (Note 5)		19		dBc
Alternate Channel Rejection (High Side)	Desired Signal at -82dBm, Alternate Modulated Channel 10MHz Above the Desired Signal, PER = 1% (Note 5)		40		dBc
Alternate Channel Rejection (Low Side)	Desired Signal at -82dBm, Alternate Modulated Channel 10MHz Below the Desired Signal, PER = 1% (Note 5)		36		dBc
Second Alternate Channel Rejection	Desired Signal at -82dBm, Second Alternate Modulated Channel Either 15MHz Above or Below, PER = 1% (Note 5)		42		dBc
Co-Channel Rejection	Desired Signal at -82dBm, Undesired Signal Is an 802.15.4 Modulated Signal at the Same Frequency, PER = 1%		-6		dBc
LO Feed Through			-55		dBm
Frequency Error Tolerance (Note 6)			± 50		ppm
Symbol Error Tolerance			± 50		ppm
Received Signal Strength Indicator (RSSI) Input Range			-90 to -10		dBm
RSSI Accuracy			± 6		dB
RSSI Resolution			1		dB

RADIO TRANSMITTER CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^\circ\text{C}$. $V_{\text{SUPPLY}} = 3.6\text{V}$ unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Output Power	Delivered to a 50 Ω load		8		dBm
High Calibrated Setting			0		dBm
Spurious Emissions	Conducted Measurement with a 50 Ω Single-Ended Load, 8dBm Output Power. All Measurements Made with Max Hold. RF Implementation Per Eterna Reference Design				
30MHz to 1000 MHz	RBW = 120kHz, VBW = 100Hz		<-70		dBm
1GHz to 12.75GHz	RBW = 1MHz, VBW = 3MHz		-45		dBm
2.4GHz ISM Upper Band Edge (Peak)	RBW = 1MHz, VBW = 3MHz		-37		dBm
2.4GHz ISM Upper Band Edge (Average)	RBW = 1MHz, VBW = 10Hz		-49		dBm
2.4GHz ISM Lower Band Edge	RBW = 100kHz, VBW = 100kHz		-45		dBc
Harmonic Emissions	Conducted Measurement Delivered to a 50 Ω Load, 8dBm Output Power, Resolution Bandwidth = 1MHz, Video Bandwidth = 1MHz. RF Implementation Per Eterna Reference Design				
2nd Harmonic			-50		dBm
3rd Harmonic			-45		dBm

SYSTEM CHARACTERISTICS The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^\circ\text{C}$. $V_{\text{SUPPLY}} = 3.6\text{V}$ unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
	RESETn Pulse Width		●	125		μs

DIGITAL I/O CHARACTERISTICS The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^\circ\text{C}$. $V_{\text{SUPPLY}} = 3.6\text{V}$ unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS (Note 7)	MIN	TYP	MAX	UNITS
V_{IL}	Low Level Input Voltage		●	-0.3	0.6	V
V_{IH}	High Level Input Voltage	(Note 8)	●	$V_{\text{SUPPLY}} - 0.3$	$V_{\text{SUPPLY}} + 0.3$	V
V_{OL}	Low Level Output Voltage	Type 1, $I_{\text{OL(MAX)}} = 1.2\text{mA}$	●		0.4	V
V_{OH}	High Level Output Voltage	Type 1, $I_{\text{OH(MAX)}} = -0.8\text{mA}$	●	$V_{\text{SUPPLY}} - 0.3$	$V_{\text{SUPPLY}} + 0.3$	V
V_{OL}	Low Level Output Voltage	Type 2, Low Drive, $I_{\text{OL(MAX)}} = 2.2\text{mA}$	●		0.4	V
V_{OH}	High Level Output Voltage	Type 2, Low Drive, $I_{\text{OH(MAX)}} = -1.6\text{mA}$	●	$V_{\text{SUPPLY}} - 0.3$	$V_{\text{SUPPLY}} + 0.3$	V
V_{OL}	Low Level Output Voltage	Type 2, High Drive, $I_{\text{OL(MAX)}} = 4.5\text{mA}$	●		0.4	V
V_{OH}	High Level Output Voltage	Type 2, High Drive, $I_{\text{OH(MAX)}} = -3.2\text{mA}$	●	$V_{\text{SUPPLY}} - 0.3$	$V_{\text{SUPPLY}} + 0.3$	V
	Input Leakage Current	Input Driven to V_{SUPPLY} or GND		50		nA
	Pull-Up/Pull-Down Resistance			50		k Ω

UART AC CHARACTERISTICS The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^\circ\text{C}$. $V_{\text{SUPPLY}} = 3.6\text{V}$ unless otherwise noted. (Note 13)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
	Permitted Rx Baud Rate Error	Both API and CLI UARTs	●	-2	2	%
	Generated Tx Baud Rate Error	Both API and CLI UARTs	●	-1	1	%
$t_{\text{RX_INTERBYTE}}$	Receive Inter-Byte Delay		●		1	Bit Period
$t_{\text{TX_INTERPACKET}}$	Transmit Inter-Packet Delay		●	1		Bit Period

TIMEn PPS AC CHARACTERISTICS The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^\circ\text{C}$. $V_{\text{SUPPLY}} = 3.6\text{V}$ unless otherwise noted. (Notes 10 and 13)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
	TIMEn PPS Period		●	1		s
	TIMEn PPS Error		●	-250	250	ns
	TIMEn Pulse Width (High or Low)		●	100		ms
$t_{\text{RFT_to_ST}}$	Time from receipt of readyForTime notification to completion of setParameter<time> command. (Note 9)		●		250	ms

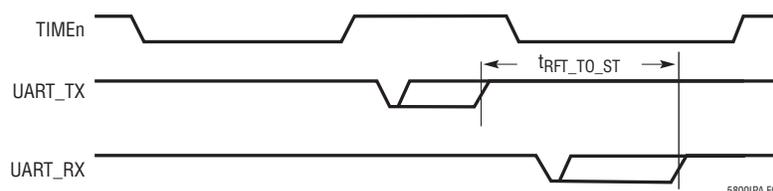


Figure 1. TIMEn PPS Timing

FLASH AC CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^\circ\text{C}$. $V_{\text{SUPPLY}} = 3.6\text{V}$ unless otherwise noted. (Note 13)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
t_{WRITE}	Time to Write a 32-Bit Word (Note 11)		●		21	μs
$t_{\text{PAGE_ERASE}}$	Time to Erase a 2kB Page (Note 11)		●		21	ms
$t_{\text{MASS_ERASE}}$	Time to Erase 256kB Flash Bank (Note 11)		●		21	ms
	Data Retention	25°C 85°C 105°C		100 20 8		Years Years Years

FLASH SPI SLAVE AC CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^\circ\text{C}$. $V_{\text{SUPPLY}} = 3.6\text{V}$ unless otherwise noted. (Note 13)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
$t_{\text{FP_EN_TO_RESET}}$	Setup from Assertion of FLASH_P_ENn to Assertion of RESETn		●	0		ns
$t_{\text{FP_ENTER}}$	Delay from the Assertion RESETn to the First Falling Edge of IPCS_SSn		●	125		μs
$t_{\text{FP_EXIT}}$	Delay from the Completion of the Last Flash SPI Slave Transaction to the Negation of RESETn and FLASH_P_ENn (Note 12)		●	10		μs
t_{SSS}	IPCS_SSn Setup to the Leading Edge of IPCS_SCK		●	15		ns
t_{SSH}	IPCS_SSn Hold from Trailing Edge of IPCS_SCK		●	15		ns
t_{CK}	IPCS_SCK Period		●	300		ns
t_{DIS}	IPCS_MOSI Data Setup		●	15		ns
t_{DIH}	IPCS_MOSI Data Hold		●	5		ns
t_{DOV}	IPCS_MISO Data Valid		●	3		ns
t_{OFF}	IPCS_MISO Data Tri-state		●		30	ns

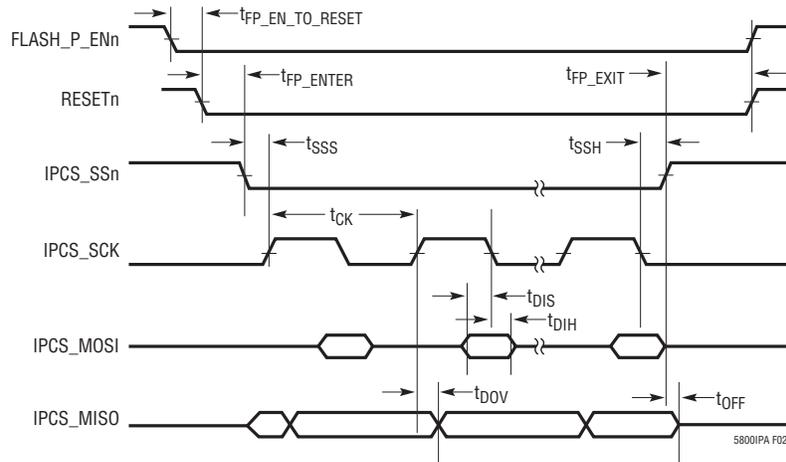


Figure 2. Flash Programming Interface Timing

ELECTRICAL CHARACTERISTICS

Note 1: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

Note 2: ESD (electrostatic discharge) sensitive device. ESD protection devices are used extensively internal to Eterna. However, high electrostatic discharge can damage or degrade the device. Use proper ESD handling precautions.

Note 3: Extended storage at high temperature is discouraged, as this negatively affects the data retention of Eterna's calibration data. See the [FLASH Data Retention](#) section for details.

Note 4: Actual RF range is subject to a number of installation-specific variables including, but not restricted to ambient temperature, relative humidity, presence of active interference sources, line-of-sight obstacles, and near-presence of objects (for example, trees, walls, signage, and so on) that may induce multipath fading. As a result, range varies.

Note 5: As Specified by IEEE Std. 802.15.4-2006: Wireless Medium Access Control (MAC) and Physical Layer (PHY) Specifications for Low-Rate Wireless Personal Area Networks (LR-WPANs)
<http://www.standards.ieee.org/findstds/standard/802.15.4-2011.html>

Note 6: IEEE Std. 802.15.4-2006 requires transmitters to maintain a frequency tolerance of better than ± 40 ppm.

Note 7: Per pin I/O types are provided in the [Pin Functions](#) section.

Note 8: VIH maximum voltage input must respect the VSUPPLY maximum voltage specification.

Note 9: See the [SmartMesh IP User's Guide](#) for the readyForTime notification to completion of setParameter<time> command definitions.

Note 10: Network time accuracy is a statistical measure and varies over the temperature range, reporting rate and the location of the device relative to the manager in the network. See the [Typical Performance Characteristics](#) section for a more detailed description.

Note 11: Code execution from flash banks being written or erased is suspended until completion of the flash operation.

Note 12: Following erase or write transfers, the IPCS SPI slave status register, 0xD7 must be polled to determine the completion time of the erase or write operation prior to negating either FLASH_P_ENn or RESETn.

Note 13: Guaranteed by design, not production tested.

TYPICAL PERFORMANCE CHARACTERISTICS

In mesh networks data can propagate from the manager to the motes, downstream, or from the motes to the manager, upstream, via a sequence of transmissions from one device to the next. As shown in Figure 4, data originating from mote P1 may propagate to the manager directly or through P2. As mote P1 may directly communicate with the manager, mote P1 is referred to as a 1-hop mote. Data originating from mote D1, must propagate through at least one other mote, P2 or P1, and as a result is referred to as a 2-hop mote. The fewest number of hops from a mote to the AP Mote determines the hop depth.

Eterna provides two mechanisms for applications to maintain a time base across a network. The synchronization performance plots that follow were generated using the more precise TIMEn input. Publishing rate is the rate a mote application sends upstream data. Synchronization improves as the publishing rate increases. Baseline synchronization performance is provided for a network operating with a publishing rate of zero. Actual performance for applications in network will improve as publishing rates increase. All synchronization testing was performed with the 1-hop mote inside a temperature chamber. Timing errors due to temperature changes and temperature differences both between the AP Mote and this mote and between this mote and its descendents therefore propagated down through the network. The synchronization of the 3-hop and 5-hop motes to the manager was thus affected by the

temperature ramps even though they were at room temperature. For 2°C/minute testing the temperature chamber was cycled between -40°C and 85°C at this rate for 24 hours. For 8°C/minute testing, the temperature chamber was rapidly cycled between 85°C and 45°C for 8 hours, followed by rapid cycling between -5°C and 45°C for 8 hours, and lastly, rapid cycling between -40°C and 15°C for 8 hours.

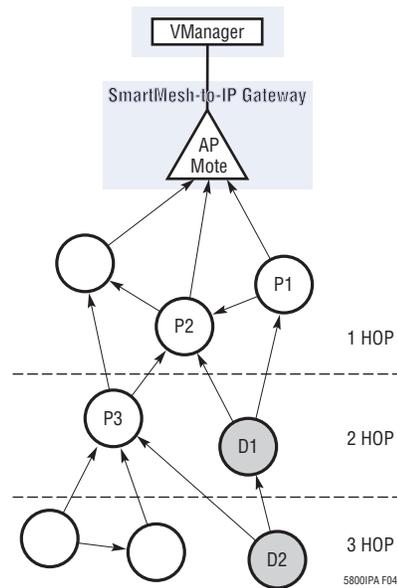


Figure 4. Example Network Graph

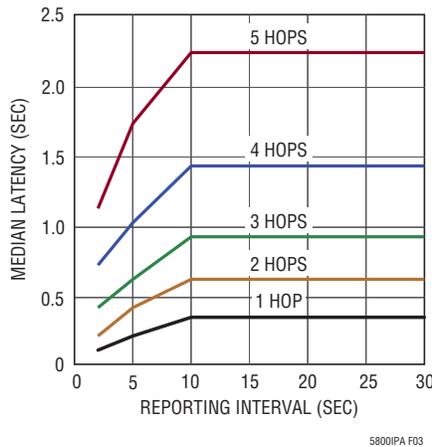
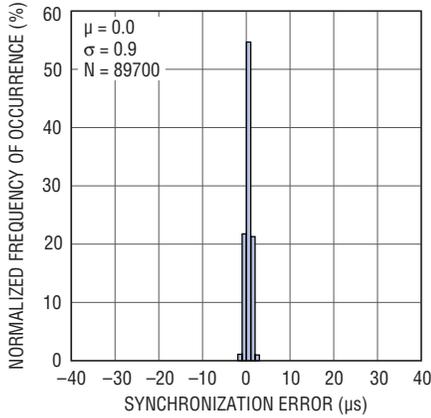


Figure 3

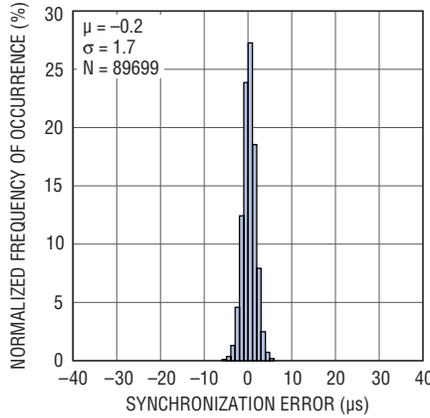
TYPICAL PERFORMANCE CHARACTERISTICS

TIMEn Synchronization Error
0 Packets/s Publishing Rate,
1 Hop, Room Temperature



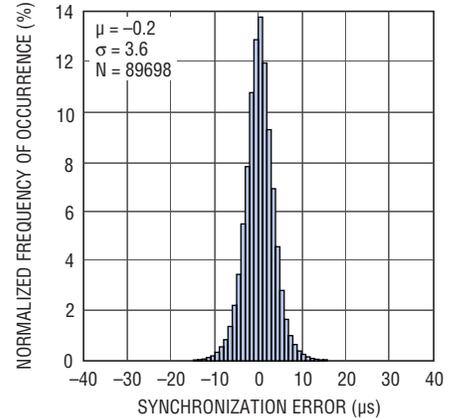
5800IPR G01

TIMEn Synchronization Error
0 Packets/s Publishing Rate,
3 Hops, Room Temperature



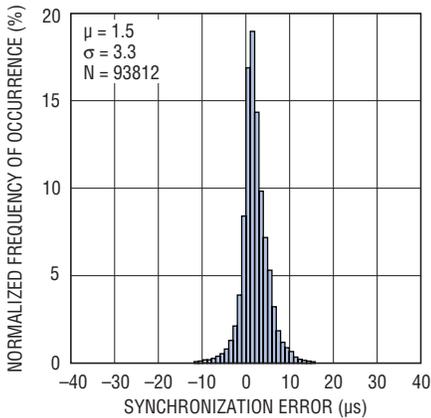
5800IPR G02

TIMEn Synchronization Error
0 Packets/s Publishing Rate,
5 Hops, Room Temperature



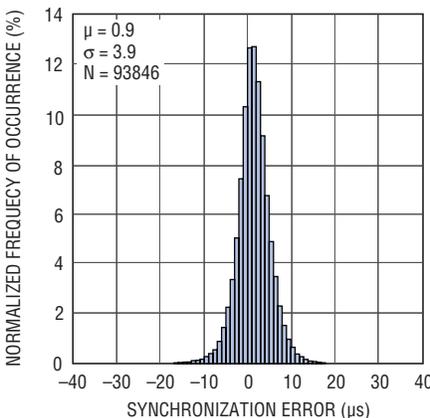
5800IPR G03

TIMEn Synchronization Error
0 Packets/s Publishing Rate,
1 Hop, 2°C/Min



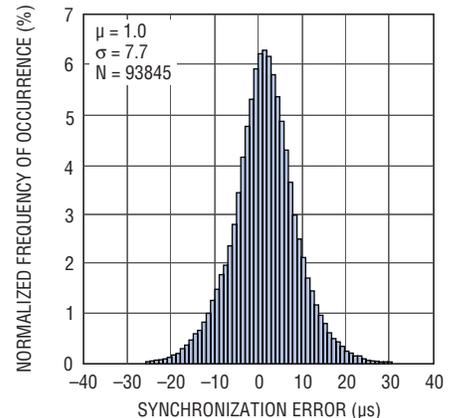
5800IPR G04

TIMEn Synchronization Error
0 Packets/s Publishing Rate,
3 Hops, 2°C/Min



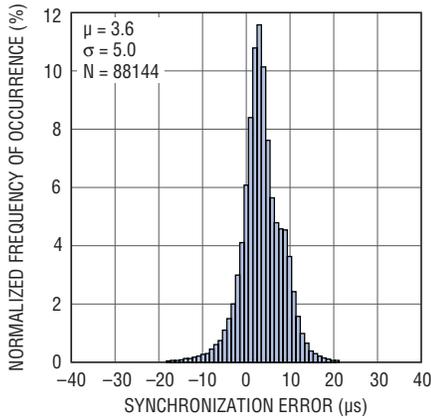
5800IPR G05

TIMEn Synchronization Error
0 Packets/s Publishing Rate,
5 Hops, 2°C/Min



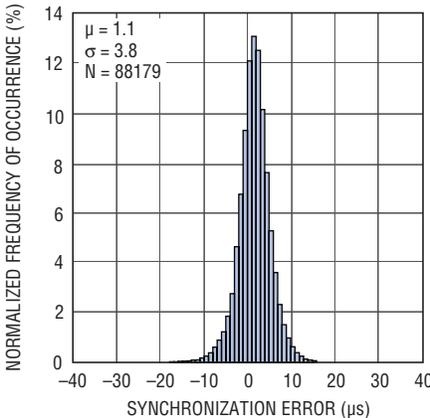
5800IPR G06

TIMEn Synchronization Error
0 Packets/s Publishing Rate,
1 Hop, 8°C/Min



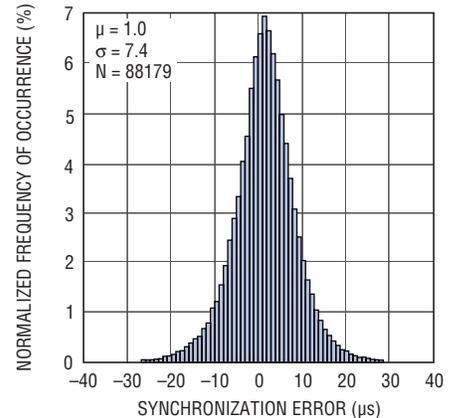
5800IPR G07

TIMEn Synchronization Error
0 Packets/s Publishing Rate,
3 Hops, 8°C/Min



5800IPR G08

TIMEn Synchronization Error
0 Packets/s Publishing Rate,
5 Hops, 8°C/Min

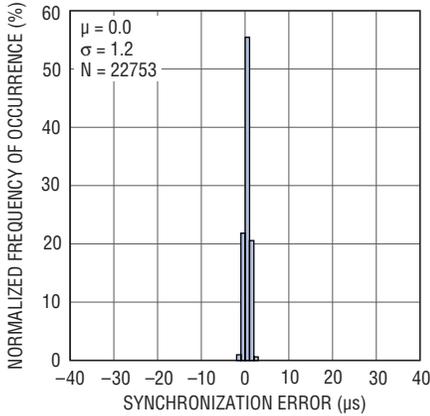


5800IPR G09

5800ipaf

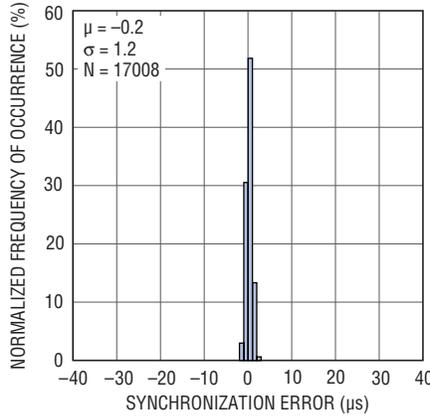
TYPICAL PERFORMANCE CHARACTERISTICS

**TIMEn Synchronization Error
1 Packet/s Publishing Rate,
1 Hop, Room Temperature**



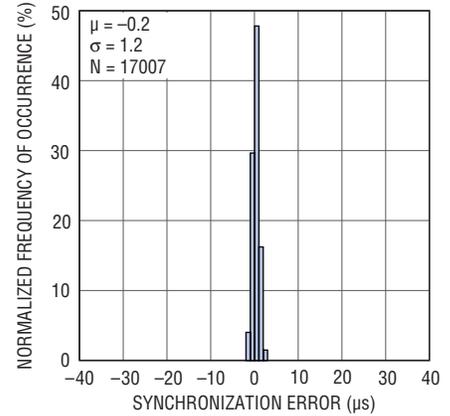
5800IPR G10

**TIMEn Synchronization Error
1 Packet/s Publishing Rate,
3 Hops, Room Temperature**



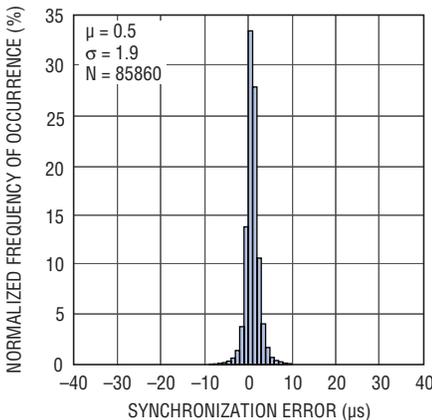
5800IPR G11

**TIMEn Synchronization Error
1 Packet/s Publishing Rate,
5 Hops, Room Temperature**



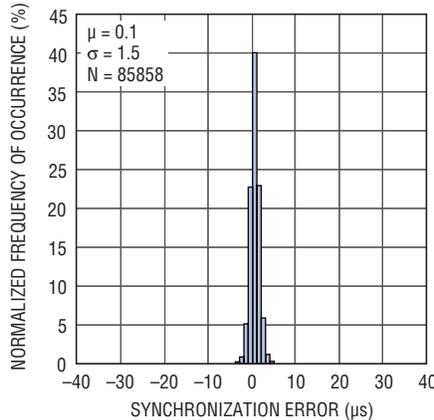
5800IPR G12

**TIMEn Synchronization Error
1 Packet/s Publishing Rate,
1 Hop, 2°C/Min**



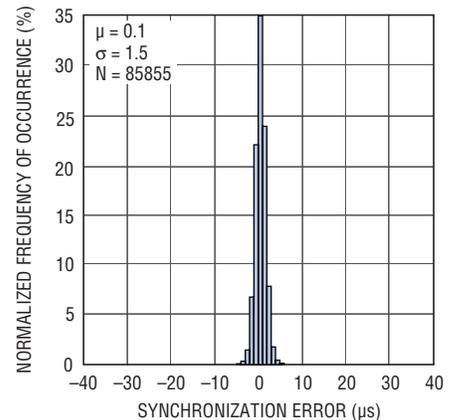
5800IPR G13

**TIMEn Synchronization Error
1 Packet/s Publishing Rate,
3 Hops, 2°C/Min**



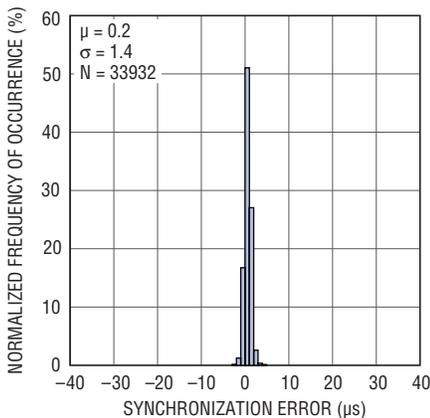
5800IPR G14

**TIMEn Synchronization Error
1 Packet/s Publishing Rate,
5 Hops, 2°C/Min**



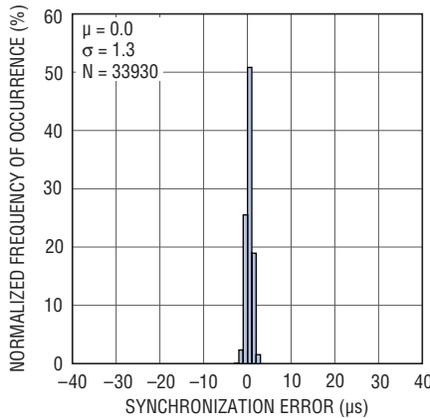
5800IPR G15

**TIMEn Synchronization Error
1 Packet/s Publishing Rate,
1 Hop, 8°C/Min**



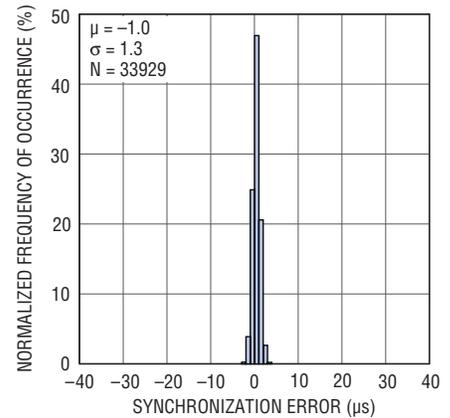
5800IPR G16

**TIMEn Synchronization Error
1 Packet/s Publishing Rate,
3 Hops, 8°C/Min**



5800IPR G17

**TIMEn Synchronization Error
1 Packet/s Publishing Rate,
5 Hops, 8°C/Min**



5800IPR G18

5800ipaf

PIN FUNCTIONS Pin functions in italics are currently not supported in software.

The following table organizes the pins by functional groups. The **NO** column provides the pin number. The second column lists the function. The **TYPE** column lists the I/O type. The **I/O** column lists the direction of the signal relative

to Eterna. The **PULL** column shows which signals have a fixed passive pull-up or pull-down. The **DESCRIPTION** column provides a brief signal description.

NO	POWER SUPPLY	TYPE	I/O	PULL	DESCRIPTION
P	GND	Power	–	–	Ground Connection, P = QFN Paddle
2	CAP_PA_1P	Power	–	–	PA DC/DC Converter Capacitor 1 Plus Terminal
3	CAP_PA_1M	Power	–	–	PA DC/DC Converter Capacitor 1 Minus Terminal
4	CAP_PA_2M	Power	–	–	PA DC/DC Converter Capacitor 2 Minus Terminal
5	CAP_PA_2P	Power	–	–	PA DC/DC Converter Capacitor 2 Plus Terminal
6	CAP_PA_3P	Power	–	–	PA DC/DC Converter Capacitor 3 Plus Terminal
7	CAP_PA_3M	Power	–	–	PA DC/DC Converter Capacitor 3 Minus Terminal
8	CAP_PA_4M	Power	–	–	PA DC/DC Converter Capacitor 4 Minus Terminal
9	CAP_PA_4P	Power	–	–	PA DC/DC Converter Capacitor 4 Plus Terminal
10	VDDPA	Power	–	–	Internal Power Amplifier Power Supply, Bypass
21	VBGAP	Power	–	–	Internal Bandgap Voltage Reference
30	VDDA	Power	–	–	Regulated Analog Supply, Bypass
31	VCORE	Power	–	–	Regulated Core Supply, Bypass
32	VOOSC	Power	–	–	Regulated Oscillator Supply, Bypass
54	VPP	Power	–	–	Internal Regulator Test Port
56	VPRIME	Power	–	–	Internal Primary Power Supply, Bypass
57	CAP_PRIME_4P	Power	–	–	Primary DC/DC Converter Capacitor 4 Plus Terminal
58	CAP_PRIME_4M	Power	–	–	Primary DC/DC Converter Capacitor 4 Minus Terminal
59	CAP_PRIME_3M	Power	–	–	Primary DC/DC Converter Capacitor 3 Minus Terminal
60	CAP_PRIME_3P	Power	–	–	Primary DC/DC Converter Capacitor 3 Plus Terminal
61	CAP_PRIME_2P	Power	–	–	Primary DC/DC Converter Capacitor 2 Plus Terminal
62	CAP_PRIME_2M	Power	–	–	Primary DC/DC Converter Capacitor 2 Minus Terminal
63	CAP_PRIME_1M	Power	–	–	Primary DC/DC Converter Capacitor 1 Minus Terminal
64	CAP_PRIME_1P	Power	–	–	Primary DC/DC Converter Capacitor 1 Plus Terminal
65	VSUPPLY	Power	–	–	Power Supply Input to Eterna

NO	RADIO	TYPE	I/O	PULL	DESCRIPTION
11	LNA_EN	1	0	–	External LNA Enable
12	RADIO_TX	1	0	–	Radio TX Active (External PA Enable/Switch Control)
13	RADIO_TXn	1	0	–	Radio TX Active (External PA Enable/Switch Control), Active Low
14	ANTENNA	–	–	–	Single-Ended Antenna Port, 50Ω

PIN FUNCTIONS

NO	CRYSTALS	TYPE	I/O	PULL	DESCRIPTION
19	OSC_32K_XOUT	Crystal	0	–	32kHz Crystal Xout
20	OSC_32K_XIN	Crystal	I	–	32kHz Crystal Xin
28	OSC_20M_XIN	Crystal	I	–	20MHz Crystal Xin
29	OSC_20M_XOUT	Crystal	0	–	20MHz Crystal Xout

NO	RESET	TYPE	I/O	PULL	DESCRIPTION
22	RESETn	1	I	UP	Reset Input, Active Low

NO	JTAG	TYPE	I/O	PULL	DESCRIPTION
23	TDI	1	I	UP	JTAG Test Data In
24	TDO	1	O	–	JTAG Test Data Out
25	TMS	1	I	UP	JTAG Test Mode Select
26	TCK	1	I	DOWN	JTAG Test Clock

NO	SPECIAL PURPOSE	TYPE	I/O	PULL	DESCRIPTION
72	TIMEn	1 (Note 14)	I	–	Time Capture Request, Active Low

NO	IPCS SPI/FLASH PROGRAMMING (NOTE 15)	TYPE	I/O	PULL	DESCRIPTION
40	IPCS_MISO	2	O	–	SPI Flash Emulation (MISO) Master In Slave Out Port
42	IPCS_MOSI	1	I	–	SPI Flash Emulation (MOSI) Master Out Slave In Port
44	IPCS_SCK	1	I	–	SPI Flash Emulation (SCK) Serial Clock Port
45	IPCS_SS _n	1	I	–	SPI Flash Emulation Slave Select, Active Low
55	FLASH_P_EN _n	1	I	UP	Flash Program Enable, Active Low

NO	API UART	TYPE	I/O	PULL	DESCRIPTION
68	UART_RX	1 (Note 14)	I	–	UART Receive
71	UART_TX	2	O	–	UART Transmit

Note 14: These inputs are always enabled and must be driven or pulled to a valid state to avoid leakage.

Note 15: Embedded programming over the IPCS SPI bus is only available when RESETn is asserted.

PIN FUNCTIONS

VSUPPLY: System and I/O Power Supply. Provides power to the chip including the on-chip DC/DC converters. The digital-interface I/O voltages are also set by this voltage. Bypass with 2.2 μ F and 0.1 μ F to ensure the DC/DC converters operate properly.

VDDPA: PA-Converter Bypass Pin. A 0.47 μ F capacitor should be connected from VDDPA to ground with as short a trace as feasible. Do not connect anything else to this pin.

VDDA: Analog-Regulator Bypass Pin. A 0.1 μ F capacitor should be connected from VDDA to ground with as short a trace as feasible. Do not connect anything else to this pin.

VCORE: Core-Regulator Bypass Pin. A 56nF capacitor should be connected from VCORE to ground with as short a trace as feasible. Do not connect anything else to this pin.

VOSC: Oscillator-Regulator Bypass Pin. A 56nF capacitor should be connected from VOSC to ground with as short a trace as feasible. Do not connect anything else to this pin.

VPP: Manufacturing Test port for internal regulator. Do not connect anything to this pin.

VPRIME: Primary-Converter Bypass Pin. A 0.22 μ F capacitor should be connected from VPRIME to ground with as short a trace as feasible. Do not connect anything else to this pin.

VBGAP: Bandgap reference output. Used for testing and calibration. Do not connect anything to this pin.

CAP_PA_1P, CAP_PA_1M Through CAP_PA_4P, CAP_PA_4M: Dedicated Power Amplifier DC/DC Converter Capacitor Pins. These pins are used when the radio is transmitting to efficiently convert VSUPPLY to the proper voltage for the power amplifier. A 56nF capacitor should be connected between each P and M pair. Trace length should be as short as feasible.

CAP_PRIME_1P, CAP_PRIME_1M Through CAP_PRIME_4P, CAP_PRIME_4M: Primary DC/DC Converter Capacitor Pins. These pins are used when the device is awake to efficiently convert VSUPPLY to the proper voltage for the three on-chip low dropout regulators. A 56nF capacitor should be connected between each P and M pair. Trace length should be as short as feasible.

ANTENNA: Multiplexed Receiver Input and Transmitter Output Pin. The impedance presented to the antenna pin should be 50 Ω , single-ended with respect to paddle ground. To ensure regulatory compliance of the final product please see the [Eterna Integration Guide](#) for filtering requirements. The antenna pin should not have a DC path to ground; AC blocking must be included if a DC-grounded antenna is used.

OSC_32K_XOUT: Output Pin for the 32kHz Oscillator. Connect to 32kHz quartz crystal. The OSC_32K_XOUT and OSC_32K_XIN traces must be well-shielded from other signals, both on the same PCB layer and lower PCB layers, as shown in Figure 5.

OSC_32K_XIN: Input for the 32kHz Oscillator. Connect to 32kHz quartz crystal. The OSC_32K_XOUT and OSC_32K_XIN traces must be well-shielded from other signals, both on the same PCB layer and lower PCB layers, as shown in Figure 5.

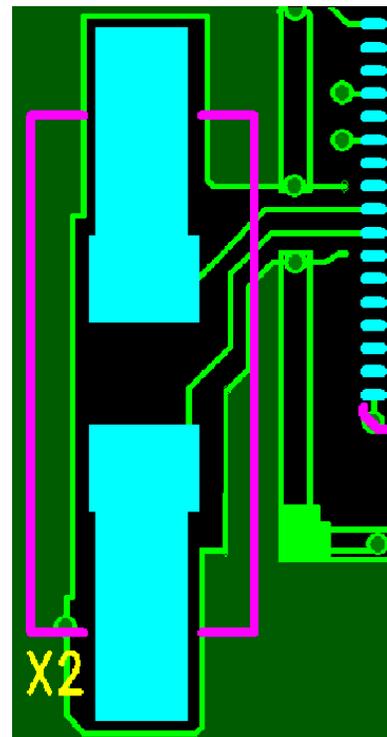


Figure 5. PCB Top Metal Layer Shielding of Crystal Signals

PIN FUNCTIONS

OSC_20M_XOUT: Output for the 20MHz Oscillator. Connect only to a supported 20MHz quartz crystal. The OSC_20M_XOUT and OSC_20M_XIN traces must be well-shielded from other signals, both on the same PCB layer and lower PCB layers, as shown in Figure 5. See the [Eterna Integration Guide](#) for supported crystals.

OSC_20M_XIN: Input for the 20MHz Oscillator. Connect only to a supported 20MHz quartz crystal. The OSC_20M_XOUT and OSC_20M_XIN traces must be well-shielded from other signals, both on the same PCB layer and lower PCB layers, as shown in Figure 5.

RESETn: The asynchronous reset signal is internally pulled up. Resetting Eterna will result in the ARM Cortex M3 rebooting and loss of network connectivity. Use of this signal for resetting Eterna is not recommended, except during power-on and in-circuit programming.

LNA_ENABLE, RADIO_TX, RADIO_TXn: Control signals generated by the autonomous MAC supporting the integration of an external LNA/PA. See the [Eterna Extended Range Reference Design](#) for implementation details.

TMS, TCK, TDI, TDO: JTAG Port Supporting Software Debug and Boundary Scan. An IEEE Std. 1149.1b-1994 compliant boundary scan definition language (BSDL) file for the WR QFN72 package can be found [here](#).

UART_RX, UART_TX: The HDLC coded API UART interface provided the primary mechanism for communication between the SmartMesh-to-IP Gateway CPU and the LTC5800.

TIMEn: The rising edge of a Pulse Per Second (PPS) signal at the TIMEn input provides the AP Mote with the network timing reference. The use of a PPS input is optional—see the Access Point section of the [SmartMesh IP User's Guide](#) for details.

UARTCO_RX, UARTCO_TX: The CLI UART provides a mechanism for monitoring, configuration and control of Eterna during operation.

FLASH_P_ENn, IPCS_SS_n, IPCS_SCK, IPCS_MISO, IPCS_SS_n: The in-circuit programming control system (IPCS) bus enables in-circuit programming of Eterna's flash memory. IPCS_SCK is a clock and should be terminated appropriately for the driving source to prevent overshoot and ringing.

OPERATION

NETWORK MANAGEMENT OPTIONS

SmartMesh IP managers provide dynamic network optimization, deterministic power management, intelligent routing, and configurable bandwidth allocation while achieving carrier class data reliability and low power operation. Linear Technology offers two solutions to manage SmartMesh IP Networks: Embedded Manager products such as the LTC5800-IPR and VManager, a software solution, which operates in tandem with one or more Access Point Motes, such as the LTC5800-IPA. For a complete description of the VManager solution please refer to the [SmartMesh IP User's Guide](#).

VMANAGER + AP MOTE BENEFITS

While the SmartMesh IP Embedded Manager form factor provides convenience for many applications, it has some limitations due to resource constraints associated with a SoC. The VManager resolves many of the limitations of a single chip solution by moving the management function to a more powerful computing platform. With the “manager” running on a range of x86 hardware platforms in a Virtual Machine, customers have the flexibility to select from a broad range of existing third party hardware, while the VManager software has the resources needed to scale. The feature highlights of this larger scale manager are as follows:

- 100% compatible with all SmartMesh IP Motes
- Increased Management capability
 - Network scale to thousands of motes
 - Network throughput scales at 40 pkt/sec per AP Mote upstream—more than 12x the embedded manager
 - Downstream throughput scales up to 17 pkt/sec per AP—up to 96x the embedded manager
 - AP Mote and management function hot redundancy

- Optional GPS Integration
 - Locking of network time to real time
 - Support of discontinuous network segments in a single network
 - Shared sense of time across all network segments

AP MOTE/VMANAGER COMMUNICATION

VManager may be connected to an AP Mote over a TCP/IP socket or directly over a COM port. COM ports may be implemented as:

- Embedded UART(s) operating at LVTTTL switching thresholds
- UART(s) over USB
- RS485

A SmartMesh-to-IP Gateway typically provides the connection between the AP Mote the VManager via a TCP/IP Socket. The corresponding TCP/IP network can take many forms, including:

- Ethernet
- Wi-Fi
- Cellular
- DSL
- Cable Modem

For detailed information on AP Mote implementation see the [SmartMesh IP User's Guide](#).

AP MOTE TIME SYNCHRONIZATION

The SmartMesh IP network protocol establishes network wide timing synchronization of all wireless devices. To accomplish this, each network must have a single time base. The LTC5800-IPA supports operating from an internal time base, network time base or an external time base. See the Access Points section of the [SmartMesh IP User's Guide](#) for the engineering trade-offs with respect to AP Mote time base options.

OPERATION

SYSTEM

The LTC5800 is the world's most energy-efficient IEEE 802.15.4 compliant platform, enabling battery and energy harvested applications. With a powerful 32-bit ARM Cortex-M3, best-in-class radio, flash, RAM and purpose-built peripherals, Eterna provides a flexible, scalable and robust networking solution for applications demanding minimal energy consumption and data reliability in even the most challenging RF environments.

Shown in Figure 6, Eterna integrates purpose-built peripherals that excel in both low operating-energy consumption and the ability to rapidly and precisely cycle between

operating and low-power states. Items in the gray shaded region labeled Analog Core correspond to the analog/RF components.

NETWORKING

The LTC5800-IPA access point mote provides the ingress/egress point at the mesh network boundary via the API UART interface. The mesh network management is handled by the VManager software, which also provides dynamic network optimization, deterministic power management, intelligent routing, and configurable bandwidth allocation while achieving carrier class data reliability and low power operation.

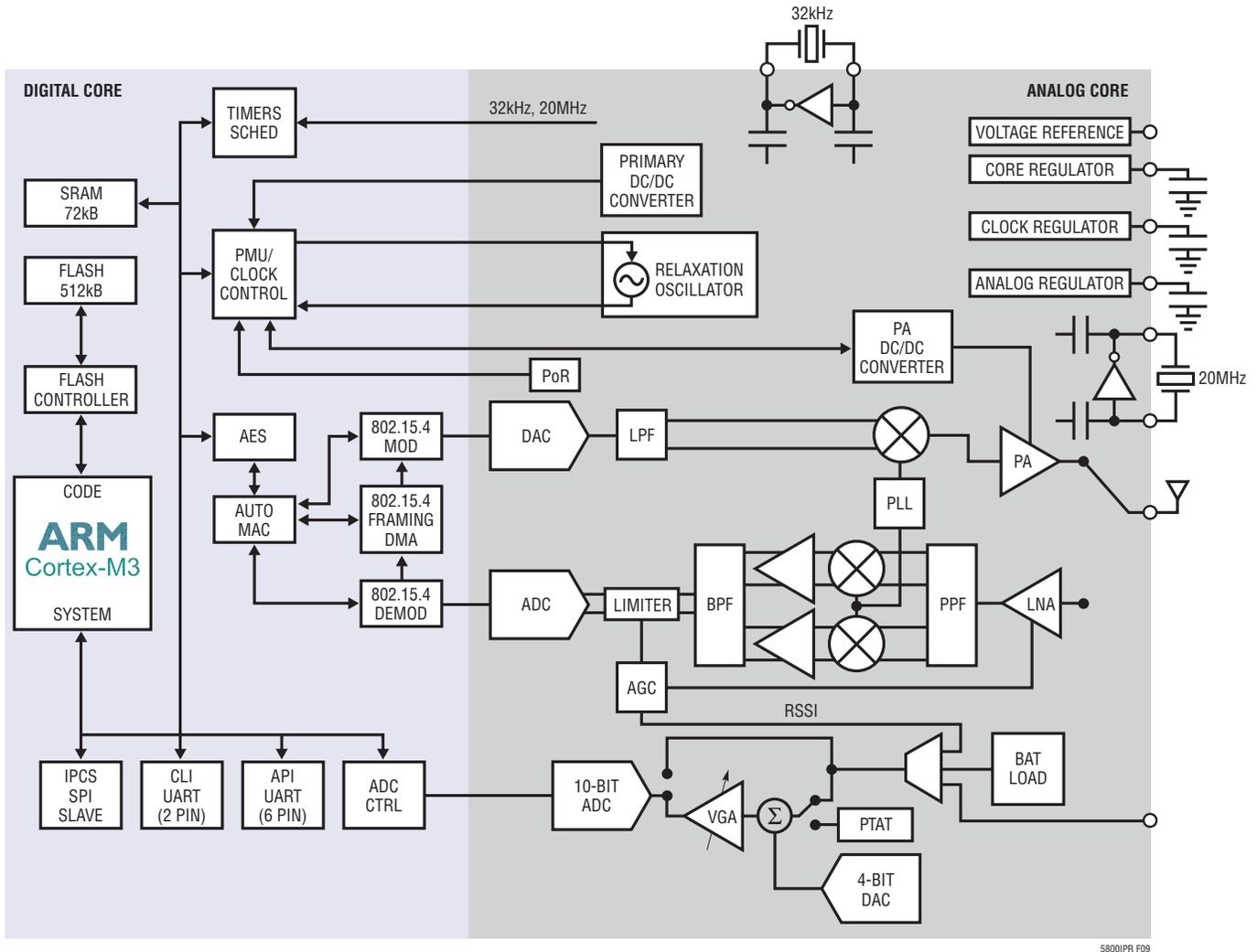


Figure 6. Eterna Block Diagram

OPERATION

CONFIGURABLE BANDWIDTH ALLOCATION

SmartMesh networks provide configurations that enable users to make bandwidth and latency versus power trade-offs both network wide and on a per device basis. This flexibility enables solutions to be tailored to the application requirements, such as request/response, fast file transfer, and alerting. Relevant configuration parameters are described in the [SmartMesh IP User's Guide](#). The Design trade-offs between network performance and current consumption are illustrated via the [SmartMesh Power and Performance Estimator](#).

POWER SUPPLY

Eterna is powered from a single pin, VSUPPLY, which powers the I/O cells and is also used to generate internal supplies. Eterna's two on-chip DC/DC converters minimize energy consumption while the device is awake. To conserve power the DC/DC converters are disabled when the device is in low power state. The integrated power supply conditioning architecture, including the two integrated DC/DC converters and three integrated low dropout regulators, provides excellent rejection of supply noise. Eterna's operating supply voltage range is high enough to support direct connection to lithium-thionyl chloride (Li-SOCl₂) sources and wide enough to support battery operation over a broad temperature range.

SUPPLY MONITORING AND RESET

Eterna integrates a power-on-reset (PoR) circuit. As the RESETn input pin is nominally configured with an internal pull-up resistor, no connection is required. Eterna includes a soft brown-out monitor that fully protects the flash from corruption in the event that power is removed while writing to flash. The integrated flash supervisory functionality, in conjunction with a fault tolerant file system, yields a robust nonvolatile storage solution.

PRECISION TIMING

Eterna's unique low power dedicated timing hardware and timing algorithms provide a significant improvement over competing 802.15.4 product offerings. This functionality provides timing precision two to three orders of magnitude better than any other low power solution available at the time of publication. Improved timing accuracy allows nodes to minimize the amount of radio listening time required to ensure packet reception thereby lowering even further the power consumed by SmartMesh networks. Eterna's patented timing hardware and timing algorithms provide superior performance over rapid temperature changes, further differentiating Eterna's reliability when compared with other wireless products. In addition, precise timing enables networks to reduce spectral dead time, increasing total network throughput.

TIME REFERENCES

Eterna includes three clock sources: an internal relaxation oscillator, a low power oscillator designed for a 32.768kHz crystal, and the radio reference oscillator designed for a 20MHz crystal.

Relaxation Oscillator

The relaxation oscillator is the primary clock source for Eterna, providing the clock for the CPU, memory subsystems, and all peripherals. The internal relaxation oscillator is dynamically calibrated to 14.3728MHz.

32.768kHz Crystal Oscillator

Once Eterna is powered up and the 32.768kHz crystal source has begun oscillating, the 32.768kHz crystal remains operational and is used as the timing basis. See the [State Diagram](#) section, for a description of Eterna's operational states.

OPERATION

20MHz Crystal Oscillator

The 20 MHz crystal source provides a frequency reference for the radio, and is automatically enabled and disabled by Eterna as needed. Eterna requires specific characterized 20MHz crystal references. See the [Eterna Integration Guide](#) for a complete list of the currently supported 20MHz crystals.

RADIO

Eterna includes the lowest power commercially available 2.4GHz IEEE 802.15.4e radio by a substantial margin. (Please refer to Radio Specifications section for power consumption numbers.) Eterna's integrated power amplifier is calibrated and temperature compensated to consistently provide power at a limit suitable for worldwide radio certifications. Additionally, Eterna uniquely includes a hardware-based autonomous MAC that handles precise sequencing of peripherals, including the transmitter, the receiver, and advanced encryption standard (AES) peripherals. The hardware-based autonomous media access controller (MAC) minimizes CPU activity, thereby further decreasing power consumption.

UARTS

The principal network interface is through the application programming interface (API) UART. A command-line interface (CLI) UART is also provided for support of test and debug functions. Both UARTs sense activity continuously, consuming virtually no power until data is transferred over the port and then automatically returning to their lowest power state after the conclusion of a transfer. The definition for packet encoding on the API UART interface can be found in the [SmartMesh IP User's Guide](#) and the CLI command definitions can be found in the [SmartMesh IP VManager CLI Guide](#).

API UART Protocol

Unlike the LTC5800-IPM or the LTC5800-IPR the LTC5800-IPA operates its API UART interface without flow control, requiring only the UART_TX and UART_RX signals. The API UART is configured at 961.6kBd, one stop bit and no parity.

CLI UART

The command line interface (CLI) UART port is a 2-wire protocol (TX and RX) that operates at a fixed 9600 baud rate with one stop bit and no parity. The CLI UART interface is intended to support command line instructions and response activity.

SECURITY

Network security is an often overlooked component of a complete network solution. Proper implementation of security protocols is significant in terms of both engineering effort and market value in an OEM product. SmartMesh-IP system solutions provide a FIPS-140 compliant encryption scheme that includes authentication and encryption at the MAC and network layers with separate keys for each mote. This not only yields end-to-end security, but if a mote is somehow compromised, communication from other motes is still secure. A mechanism for secure key exchange allows for key rotation. To prevent physical attacks, Eterna includes hardware support for electronically locking devices, thereby preventing access to Eterna's flash and RAM memory and thus the keys and code stored therein. This lock-out feature also provides a means to securely unlock a device should support of a product require access. For details see the [Board Specific Configuration Guide](#).

FLASH PROGRAMMING

This product is provided without software programmed into the device. OEMs will need to program software images during development and manufacturing. Eterna's software

OPERATION

images are loaded via the In-circuit Programming Control System (IPCS) SPI interface. Sequencing of RESETn and FLASH_P_ENn, as described in the [Flash SPI Slave A/C Characteristics](#) table, places Eterna in a state emulating a serial flash to support in-circuit programming. Hardware and software for supporting development and production programming of devices is described in the Eterna Serial Programmer Guide. The serial protocol, SPI, and timing parameters are described in the [Flash SPI Slave A/C Characteristics](#) table.

FLASH DATA RETENTION

Eterna contains internal flash (non-volatile memory) to store calibration results, unique ID, configuration settings and software images. Flash retention is specified over the operating temperature range. See Electrical Characteristics and Absolute Maximum Ratings sections.

Non destructive storage outside the operating temperature range of -55°C to 105°C is possible; however, this may result in a degradation of retention characteristics.

The degradation in flash retention for temperatures exceeding specified temperatures can be approximated by calculating the dimensionless acceleration factor using the following equation.

$$AF = e^{\left[\left(\frac{E_a}{k} \right) \left(\frac{1}{T_{USE}+273} - \frac{1}{T_{STRESS}+273} \right) \right]}$$

Where:

AF = acceleration factor

Ea = activation energy = 0.6eV

k = $8.625 \cdot 10^{-5} \text{eV}/^{\circ}\text{K}$

T_{USE} = is the specified temperature retention in $^{\circ}\text{C}$

T_{STRESS} = actual storage temperature in $^{\circ}\text{C}$

Example: Calculate the effect on retention when storing at a temperature of 125°C .

T_{STRESS} = 125°C

T_{USE} = 85°C

AF = 7.1

So the overall retention of the flash would be degraded by a factor of 7.1, reducing data retention from 20 years at 85°C to 2.8 years at 125°C .

STATE DIAGRAM

In order to provide capabilities and flexibility, the AP Mote operates in various states, as shown in Figure 7, and described in this section. State transitions shown in red are not recommended.

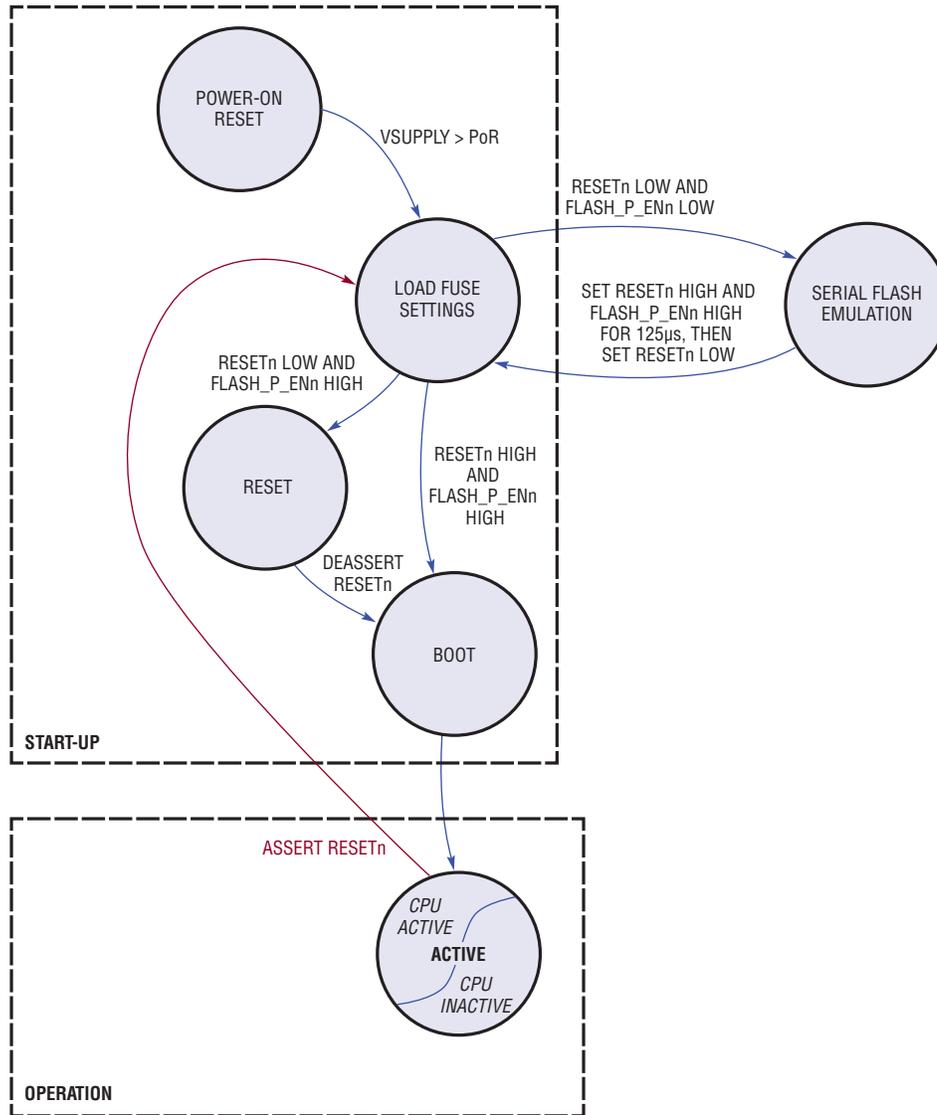
Fuse Table

Eterna's Fuse Table is a 2kB page in flash that contains two data structures. One structure supports hardware configuration immediately following power-on reset or the assertion of RESETn. The second structure supports configuration of software board support parameters. Fuse Tables are generated via the Fuse Table application described in the [Board Specific Configuration Guide](#). Hardware configuration of I/O immediately following power-on reset provides a method to minimize leakage due to floating nets prior to software configuration. I/O leakage can contribute hundreds of microamperes of leakage per input, potentially stressing current limited supplies. Examples of software board support parameters include setting of UART modes, clock sources and trim values. Fuse Tables are loaded into flash using the same software and in-circuit programmer used to load software images as described in the [Eterna Serial Programmer Guide](#).

Start-Up

Start-up occurs as a result of either crossing the power-on reset threshold or asserting RESETn. After the completion of power-on reset or the falling edge of an internally synchronized RESETn, Eterna loads its Fuse Table which, as described in the previous section, includes configuring I/O direction. In this state, Eterna checks the state of the FLASH_P_ENn and RESETn pins and enters the serial flash emulation mode if both signals are asserted. If the FLASH_P_ENn pin is not asserted but RESETn is asserted, Eterna automatically reduces its energy consumption to a minimum until RESETn is released. Once RESETn is de-asserted, Eterna goes through a boot sequence, and then enters the Active state.

OPERATION



5800IPA F07

Figure 7. Eterna AP Mote State Diagram

Serial Flash Emulation

When both RESETn and FLASH_P_ENn are asserted, Eterna disables normal operation and enters a mode to emulate the operation of a serial flash. In this mode, its flash can be programmed.

Operation

Once Eterna has completed start-up Eterna transitions to the Operational states with either the CPU active or inactive.

Active State

In the Active State, Eterna's relaxation oscillator is running and peripherals are enabled as needed.

APPLICATIONS INFORMATION

REGULATORY AND STANDARDS COMPLIANCE

Radio Certification

Eterna is suitable for systems targeting compliance with worldwide radio frequency regulations: ETSI EN 300 328 and EN 300 440 class 2 (Europe), FCC CFR47 Part 15 (US), and ARIB STD-T66 (Japan). Application Programming Interfaces (APIs) supporting regulatory testing are provided on both the API and CLI UART interfaces. The [Eterna Certification User Guide](#) provides:

- Reference information required for certification
- Test plans for common regulatory test cases
- Example CLI API calls
- Sample manual language and example label

Compliance to Restriction of Hazardous Substances (RoHS)

Restriction of Hazardous Substances 2 (RoHS 2) is a directive that places maximum concentration limits on the use of cadmium (Cd), lead (Pb), hexavalent chromium (Cr⁺⁶), mercury (Hg), Polybrominated Biphenyl (PBB), and Polybrominated Diphenyl Ethers (PBDE). Linear Technology is committed to meeting the requirements of the European Community directive 2011/65/EU.

This product has been specifically designed to utilize RoHS-compliant materials and to eliminate or reduce the use of restricted materials to comply with 2011/65/EU.

The RoHS-compliant design features include:

- RoHS-compliant solder for solder joints
- RoHS-compliant base metal alloys
- RoHS-compliant precious metal plating
- RoHS-compliant cable assemblies and connector choices
- Lead-free LGA package
- Halogen-free mold compound
- RoHS-compliant and 245°C re-flow compatible

Note: Customers may elect to use certain types of lead-free solder alloys in accordance with the European Community directive 2011/65/EU. Depending on the type of solder paste chosen, a corresponding process change to optimize reflow temperatures may be required.

SOLDERING INFORMATION

Eterna is suitable for both eutectic PbSn and RoHS-6 reflow. The maximum reflow soldering temperature is 260 °C. A more detailed description of layout recommendations, assembly procedures and design considerations is included in the [Eterna Integration Guide](#).

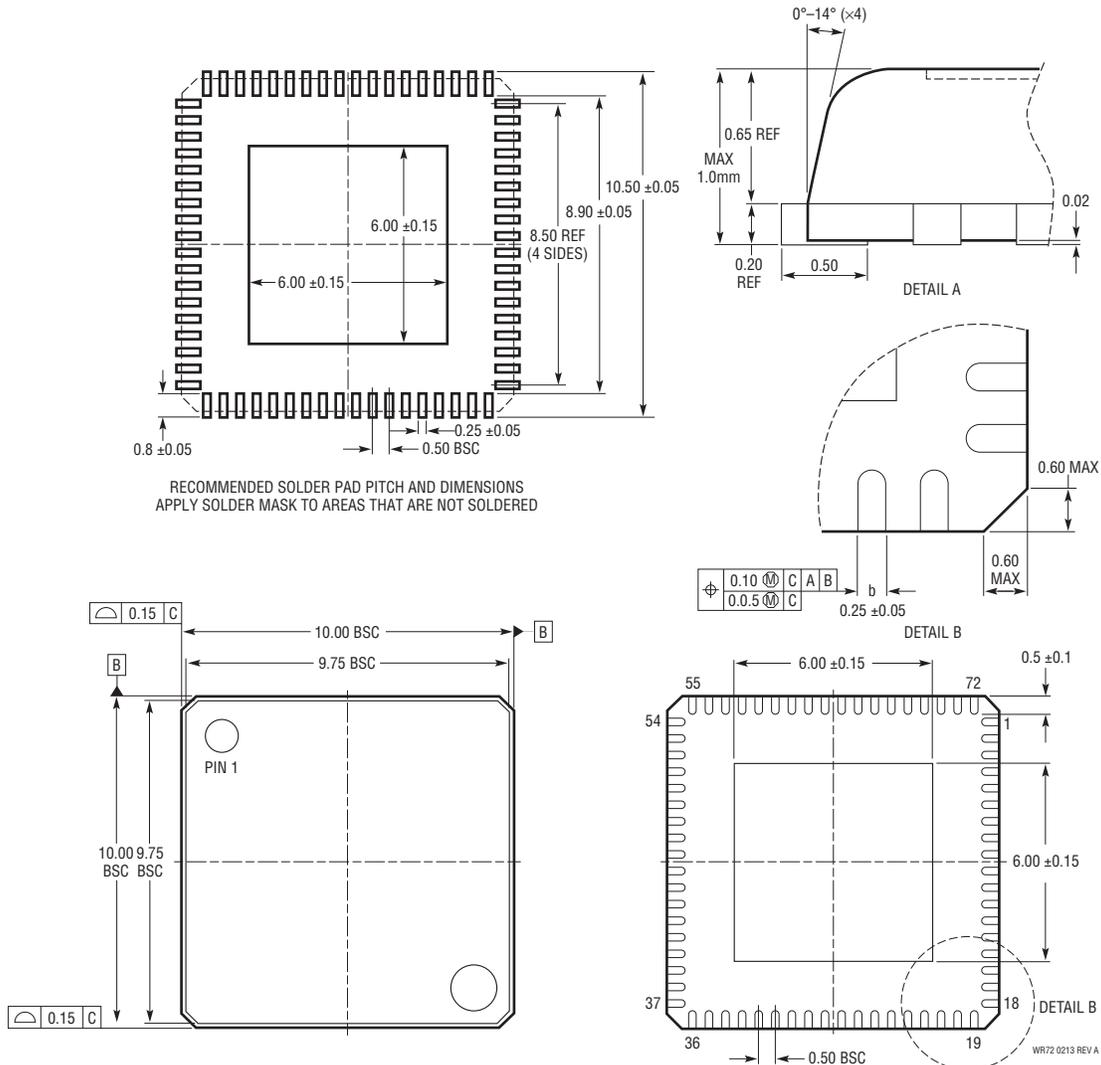
RELATED DOCUMENTATION

TITLE	LOCATION	DESCRIPTION
SmartMesh IP User's Guide	http://www.linear.com/docs/41880	Theory of operation for SmartMesh IP networks and motes
SmartMesh IP VManager API Guide	http://www.linear.com/docs/47487	Definitions of the applications interface commands available over the API UART
SmartMesh IP VManager CLI Guide	http://www.linear.com/docs/47486	Definitions of the command line interface commands available over the CLI UART
Eterna Integration Guide	http://www.linear.com/docs/41874	Recommended practices for designing with the LTC5800
Eterna Serial Programmer Guide	http://www.linear.com/docs/41876	User's guide for the Eterna serial programmer used for in circuit programming of the LTC5800
Board Specific Configuration Guide	http://www.linear.com/docs/41875	User's guide for the Eterna Board Specific Configuration application, used to configure the board specific parameters
Eterna Certification User Guide	http://www.linear.com/docs/42918	The essential documentation necessary to complete radio certifications, including examples for common test cases
SmartMesh IP Tools Guide	http://www.linear.com/docs/42453	The user's guide for all IP related tools, and specifically the definition for the on-chip application protocol (OAP)

PACKAGE DESCRIPTION

Please refer to <http://www.linear.com/product/LTC5800-IPA#packaging> for the most recent package drawings.

WR Package
72-Lead QFN (10mm × 10mm)
 (Reference LTC DWG # 05-08-1930 Rev A)

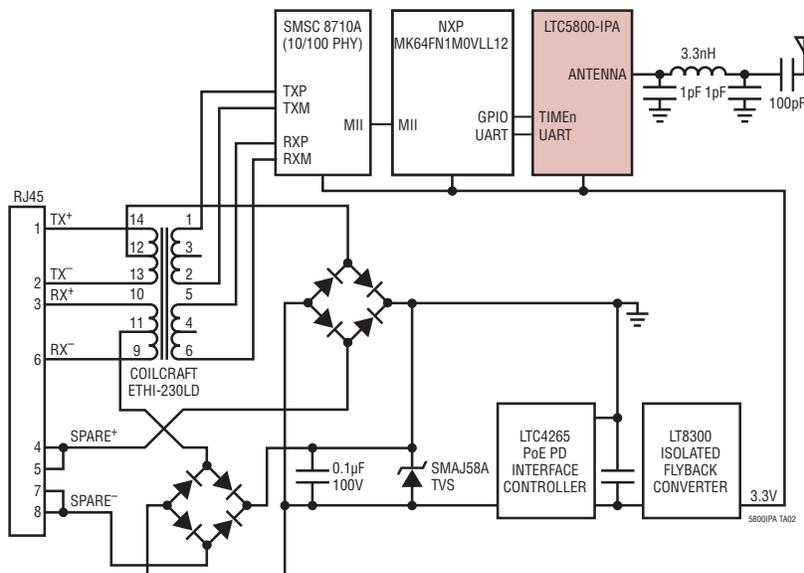


RECOMMENDED SOLDER PAD PITCH AND DIMENSIONS
 APPLY SOLDER MASK TO AREAS THAT ARE NOT SOLDERED

- NOTE:
1. DRAWING CONFORMS TO JEDEC PACKAGE OUTLINE MO-220
 2. DIMENSION "b" APPLIES TO METALIZED TERMINAL AND IS MEASURED BETWEEN 0.15mm AND 0.30mm FROM THE TERMINAL TIP. IF THE TERMINAL HAS OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL, THE DIMENSION B SHOULD NOT BE MEASURED IN THAT RADIUS AREA
 3. ALL DIMENSIONS ARE IN MILLIMETERS
 4. DIMENSIONS OF EXPOSED PAD ON BOTTOM OF PACKAGE DO NOT INCLUDE MOLD FLASH. MOLD FLASH, IF PRESENT, SHALL NOT EXCEED 0.20mm ON ANY SIDE, IF PRESENT
 5. DRAWING NOT TO SCALE

TYPICAL APPLICATION

Power over Ethernet SmartMesh Access Point



RELATED PARTS

PART NUMBER	DESCRIPTION	COMMENTS
LTC5800-IPM	IP Wireless Mote	Ultralow Power Mote, 72-Lead 10mm × 10mm QFN
LTC5800-IPR	IP Wireless Mesh Embedded Manager PCB Module with Chip Antenna	Includes Modular Radio Certification in the United States, Canada, Europe, Japan, South Korea, Taiwan, India, Australia and New Zealand
LTP5901-IPM	IP Wireless Mesh Mote PCB Module with Chip Antenna	Includes Modular Radio Certification in the United States, Canada, Europe, Japan, South Korea, Taiwan, India, Australia and New Zealand
LTP5902-IPM	IP Wireless Mesh Mote PCB Module with MMCX Antenna Connector	Includes Modular Radio Certification in the United States, Canada, Europe, South Korea, Japan, Taiwan, India, Australia and New Zealand
LTP5902-IPR	IP Wireless Mesh Embedded Manager PCB Module with MMCX Antenna Connector	Includes Modular Radio Certification in the United States, Canada, Europe, South Korea, Japan, Taiwan, India, Australia and New Zealand
LTP5901-IPR	IP Wireless Mesh Embedded Manager PCB Module with Chip Antenna	Includes Modular Radio Certification in the United States, Canada, Europe, Japan, South Korea, Taiwan, India, Australia and New Zealand
LTC4265	IEEE 802.3 at High Power PD Interface Controller with 2-Event Classification Recognition	IEEE 802.3af/at Powered Device (PD) Controller with IEEE 802.3at 2-event Classification Signaling, Programmable Classification Current, Flexible Auxiliary Power Support Using SHDN Pin and Rugged 100V Onboard MOSFET
LT8300	Micropower Isolated Flyback Converter	Isolated Flyback Converter with 6V to 100V Input Voltage Range and 260mA, 150V Internal DMOS Power Switch